

FDP51N25 / FDPF51N25 **250V N-Channel MOSFET**

Features

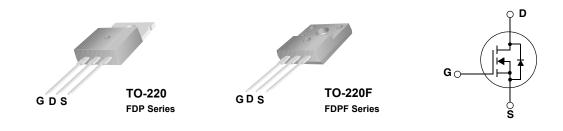
- 51A, 250V, $R_{DS(on)}$ = 0.06 Ω @V_{GS} = 10 V Low gate charge (typical 55 nC)
- Low Crss (typical 63 pF)
- · Fast switching
- Improved dv/dt capability



Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.



Absolute Maximum Ratings

Symbol		Parameter		FDP51N25	FDPF51N25	Unit
V _{DSS}	Drain-Source Voltage		250		V	
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		51 30	51* 30*	A A
I _{DM}	Drain Current	- Pulsed	(Note 1)	204	204*	А
V _{GSS}	Gate-Source voltage		± 30		V	
E _{AS}	Single Pulsed Avalanche Energy ((Note 2)	1111		mJ
I _{AR}	Avalanche Current		(Note 1)	51		А
E _{AR}	Repetitive Avalanche Energy		(Note 1)	32		mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	4.5		V/ns
P _D	Power Dissipation	(T _C = 25°C) - Derate above 25°C		320 3.7	38 0.3	W W/°C
T _{J,} T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C	
Τ _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		Э,	300		°C

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FDP51N25	FDPF51N25	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction-to-Case	0.39	3.3	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5		°C/W
R_{\thetaJA}	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/WJ

July 2008

UniFET™

—

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP51N25	FDP51N25	TO-220	-	-	50
FDPF51N25	FDPF51N25	TO-220F	-	-	50

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Off Charac	teristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_{D} = 250 μ A, T_{J} = 25°C	250			V
ΔΒV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced to 25°C		0.25		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 250V, V_{GS} = 0V$ $V_{DS} = 200V, T_{C} = 125^{\circ}C$			1 10	μΑ μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V			-100	nA
On Charac	teristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 25.5A		0.048	0.060	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40V, I _D = 25.5A (Note 4)		43		S
Dynamic C	haracteristics					
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V,		2620	3410	pF
C _{oss}	Output Capacitance	f = 1.0MHz		530	690	pF
C _{rss}	Reverse Transfer Capacitance			63	90	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 125V, I _D = 51A		62	135	ns
t _r	Turn-On Rise Time	$R_{G} = 25\Omega$		465	940	ns
t _{d(off)}	Turn-Off Delay Time			98	205	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		130	270	ns
Qg	Total Gate Charge	V _{DS} = 200V, I _D = 51A		55	70	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10V		16		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		27		nC
Drain-Sour	rce Diode Characteristics and Maximur	n Ratings				1
I _S Maximum Continuous Drain-Source Diode Forward Current					51	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				204	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 51A			1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 51A		178		ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$ (Note 4)		4.0		μC

Notes:

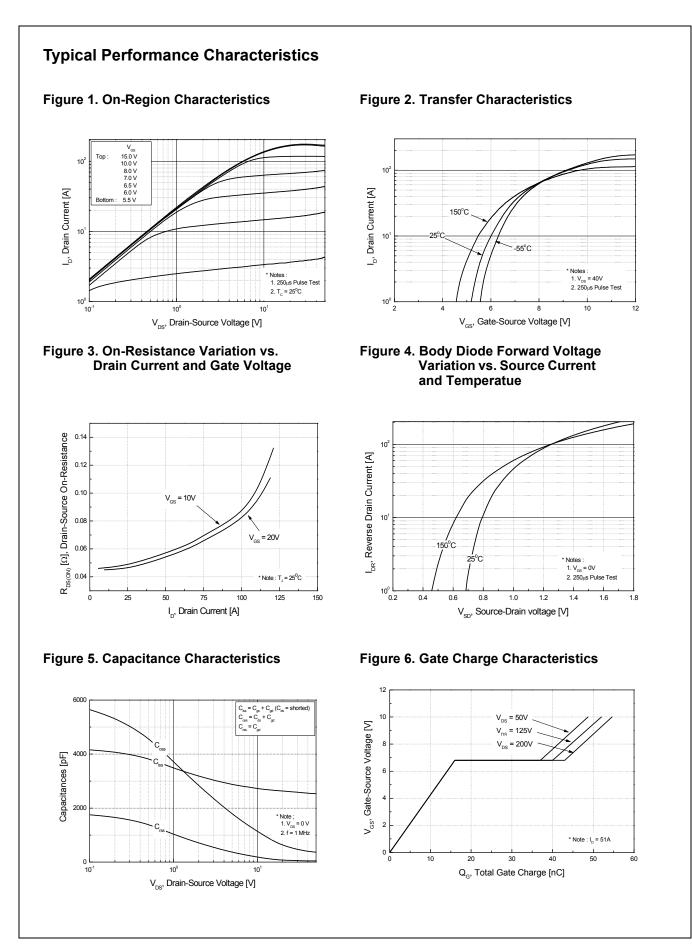
1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. L = 0.68mH, I_{AS} = 51A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25°C

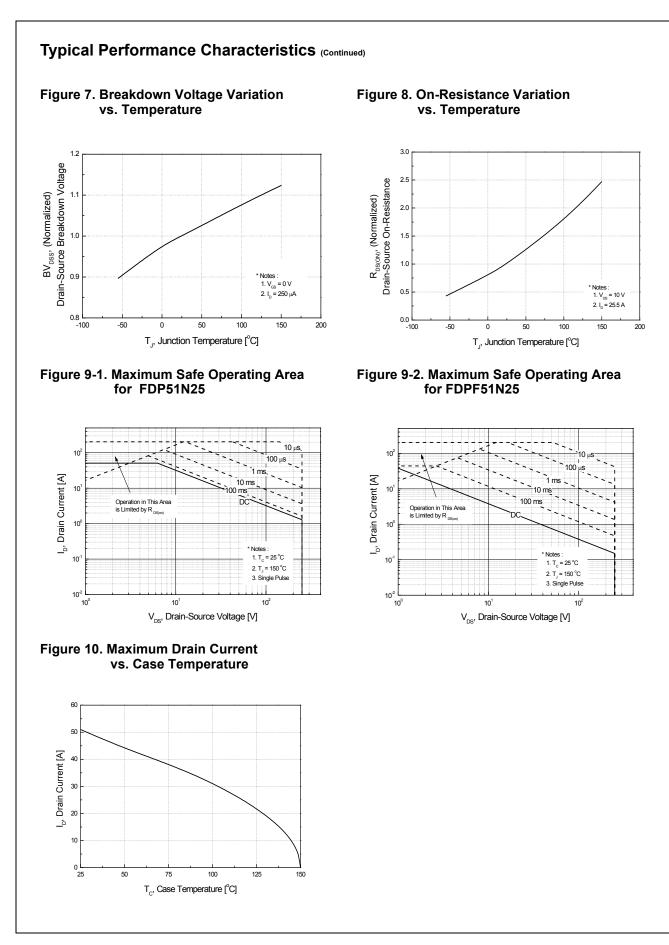
3. $I_{SD} \leq$ 51A, di/dt \leq 200A/µs, $V_{DD} \leq BV_{DSS},$ Starting T_J = 25°C

4. Pulse Test: Pulse width $\leq 300 \mu s,$ Duty Cycle $\leq 2\%$

5. Essentially Independent of Operating Temperature Typical Characteristics



3



Typical Performance Characteristics (Continued) Figure 11-1. Transient Thermal Response Curve for FDP51N25

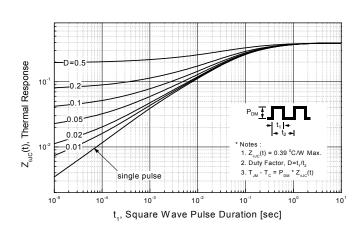
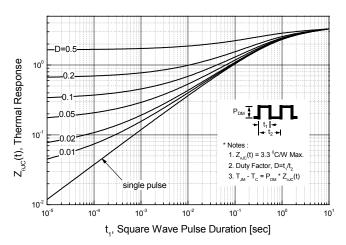
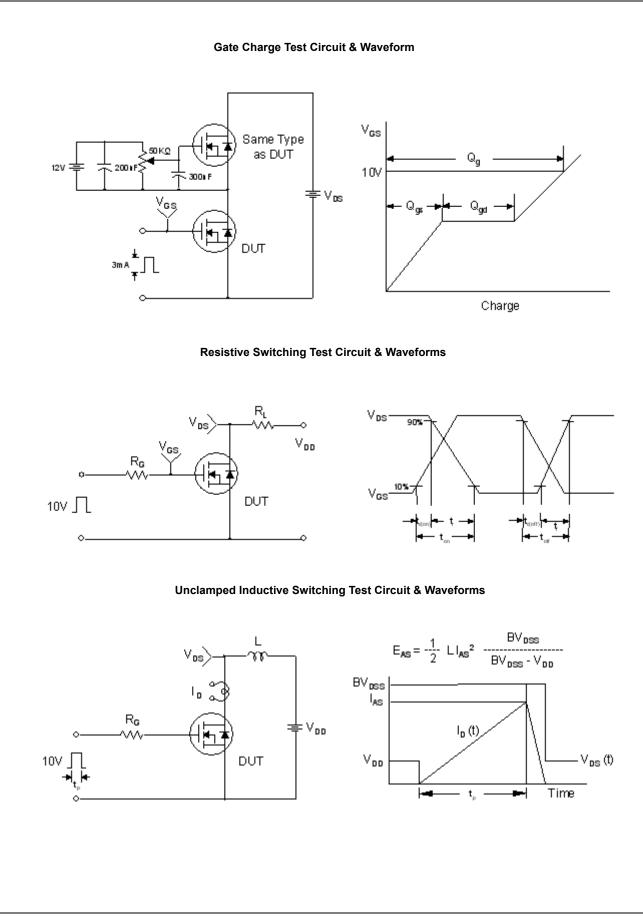


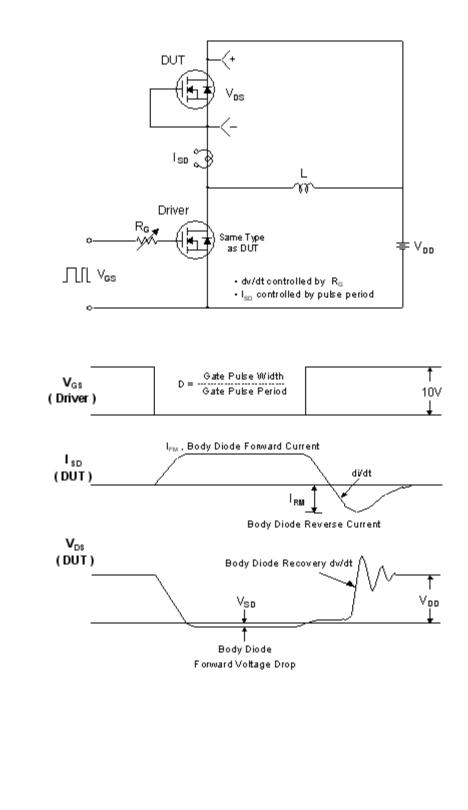
Figure 11-2. Transient Thermal Response Curve for FDPF51N25

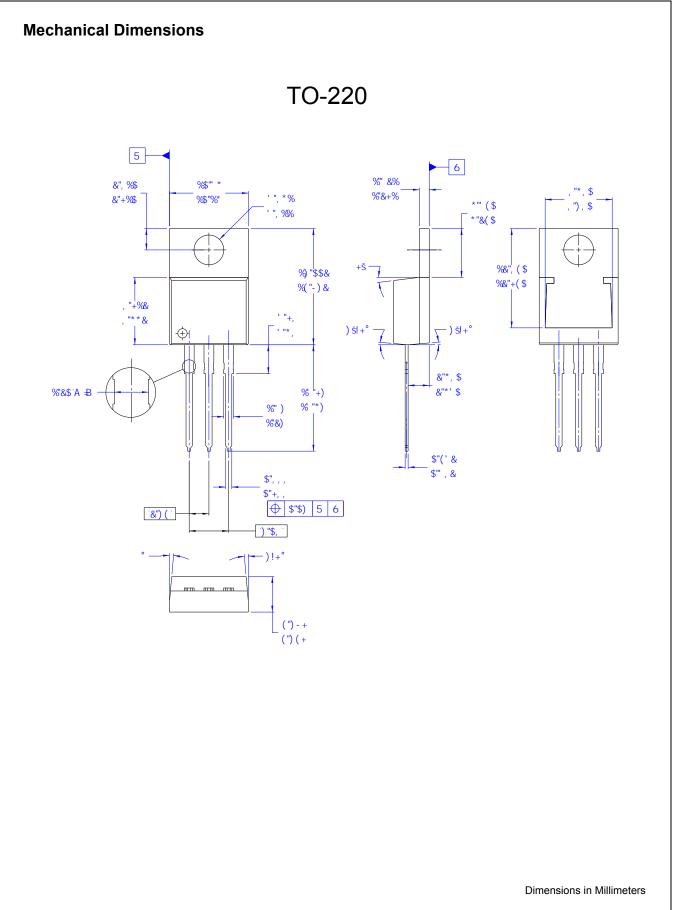


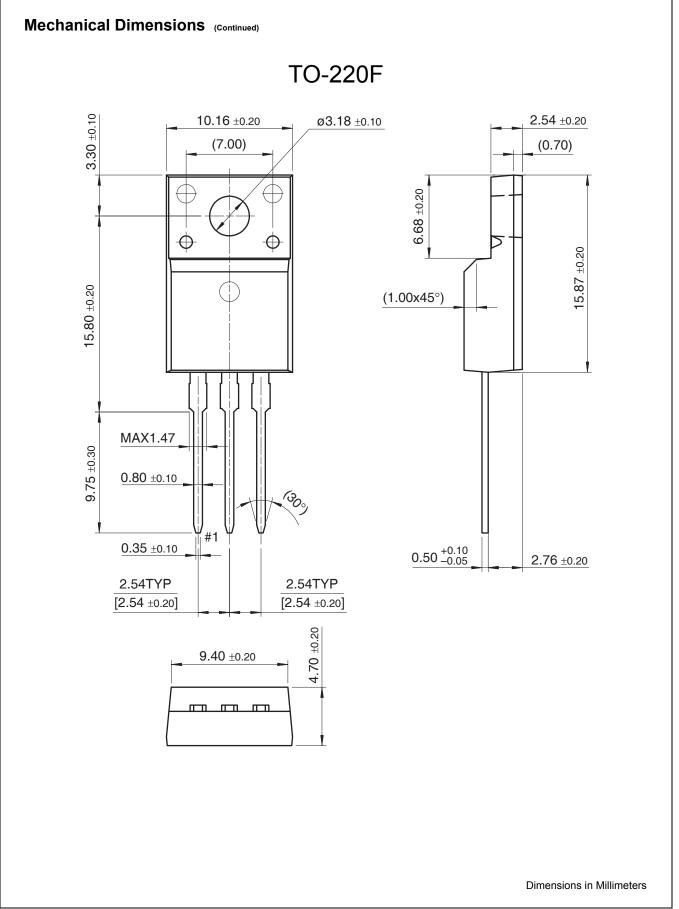


FDP51N25 / FDPF51N25 250V N-Channel MOSFET

Peak Diode Recovery dv/dt Test Circuit & Waveforms







9



SEMICONDUCTOR

TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidianries, and is not intended to be an exhaustive list of all such trademarks.

Build it Now™	FPS™	PDP SPM™	The Power Franchise [®]
CorePLUS™	F-PFS™	Power-SPM™	the
CorePOWER™	FRFET [®]	PowerTrench [®]	puwer
CROSSVOLT™	Global Power Resource SM	Programmable Active Droop™	franchise
CTL™	Green FPS™	QFET®	TinyBoost™
Current Transfer Logic™	Green FPS™ e-Series™	QS™	TinyBuck™
EcoSPARK [®]	GTO™	Quiet Series™	TinyLogic®
EfficentMax™	IntelliMAX™	RapidConfigure™	TINYOPTO™ Tiny Down of M
EZSWITCH™ *	ISOPLANAR™	Saving our world, 1mW at a time™	TinyPower™ Tiny Division
	MegaBuck™	SmartMax™	TinyPWM™
<u></u> ,	MICROCOUPLER™	SMART START™	TinyWire™
R	MicroFET™	SPM®	\mathcal{M}
F	MicroPak™	STEALTH™	✓ SerDes [™]
Fairchild®	MillerDrive™	SuperFET™	UHC®
Fairchild Semiconductor [®]	MotionMax™	SuperSOT™-3	Ultra FRFET™
FACT Quiet Series™	Motion-SPM™	SuperSOT™-6	UniFET™
FACT®	OPTOLOGIC®	SuperSOT™-8	VCX™
FAST®	OPTOPLANAR [®]	SuperMOS™	VisualMax™
FastvCore™	®	SyncFET™	
FlashWriter [®] *	(1)	2	

* EZSWITCH™ and FlashWriter[®] are trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

EARCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Farichild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Farichild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.